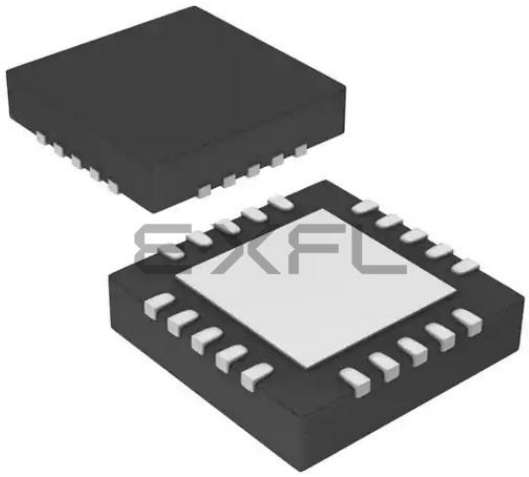

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 12x10b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1708t-i-ml

2.0 ENHANCED MID-RANGE CPU

This family of devices contain an enhanced mid-range 8-bit CPU core. The CPU has 49 instructions. Interrupt capability includes automatic context saving. The hardware stack is 16 levels deep and has Overflow and Underflow Reset capability. Direct, Indirect, and Relative addressing modes are available. Two File Select Registers (FSRs) provide the ability to read program and data memory.

- Automatic Interrupt Context Saving
- 16-level Stack with Overflow and Underflow
- File Select Registers
- Instruction Set

FIGURE 2-1: CORE BLOCK DIAGRAM

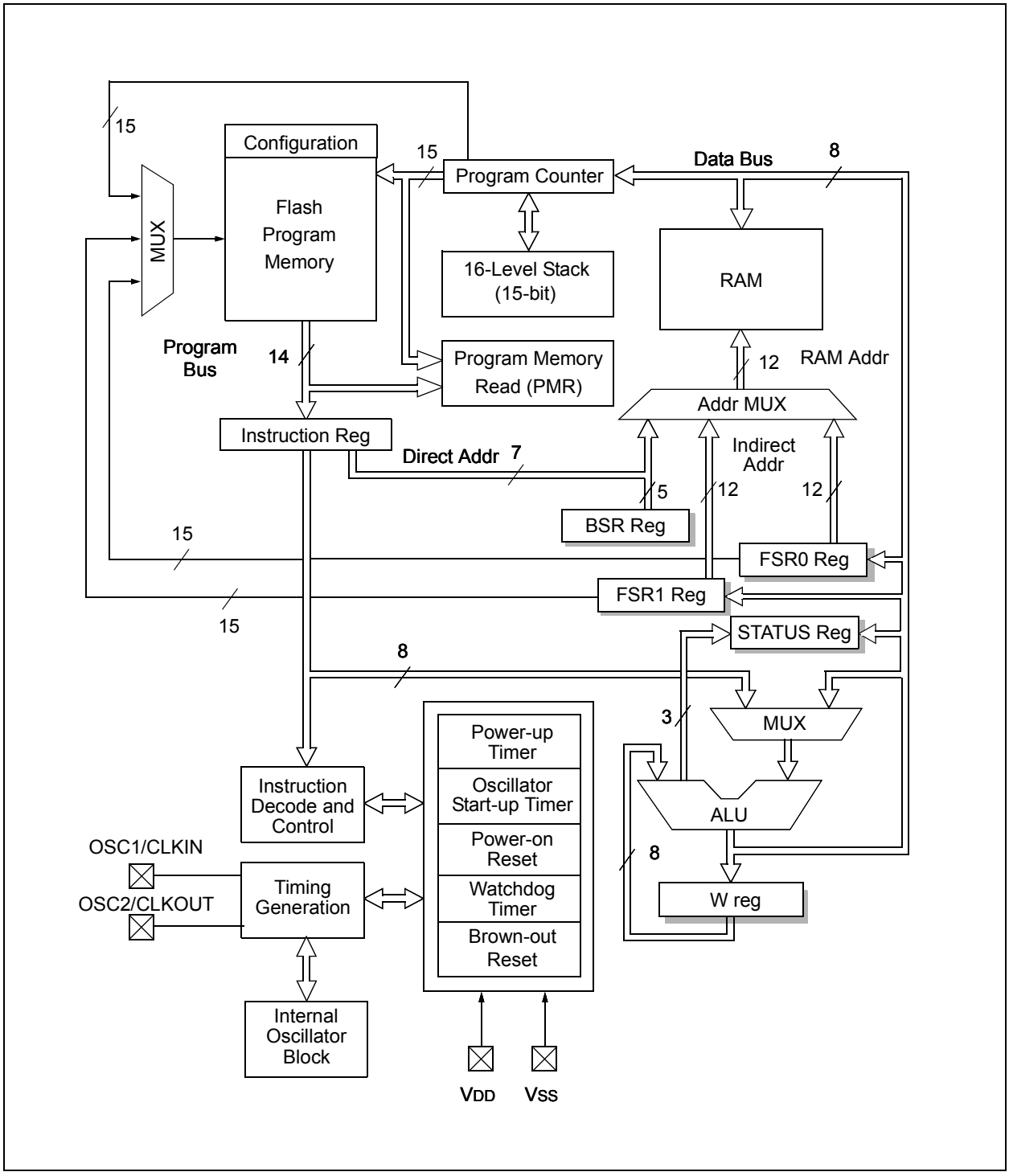
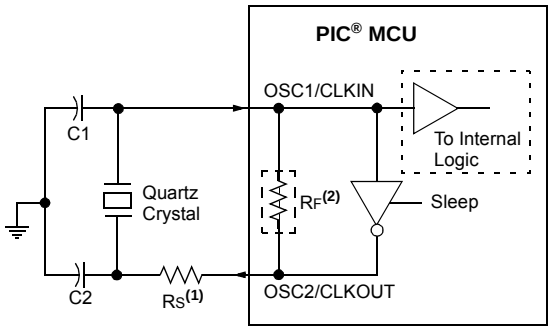


FIGURE 6-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

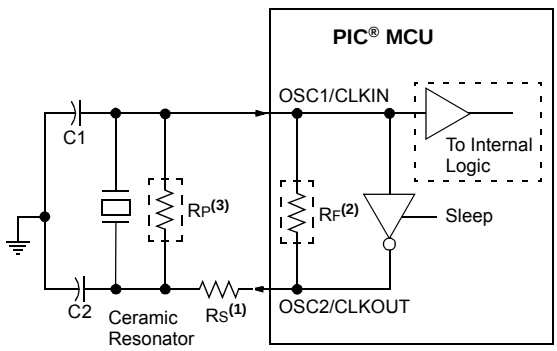
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Application Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 6-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

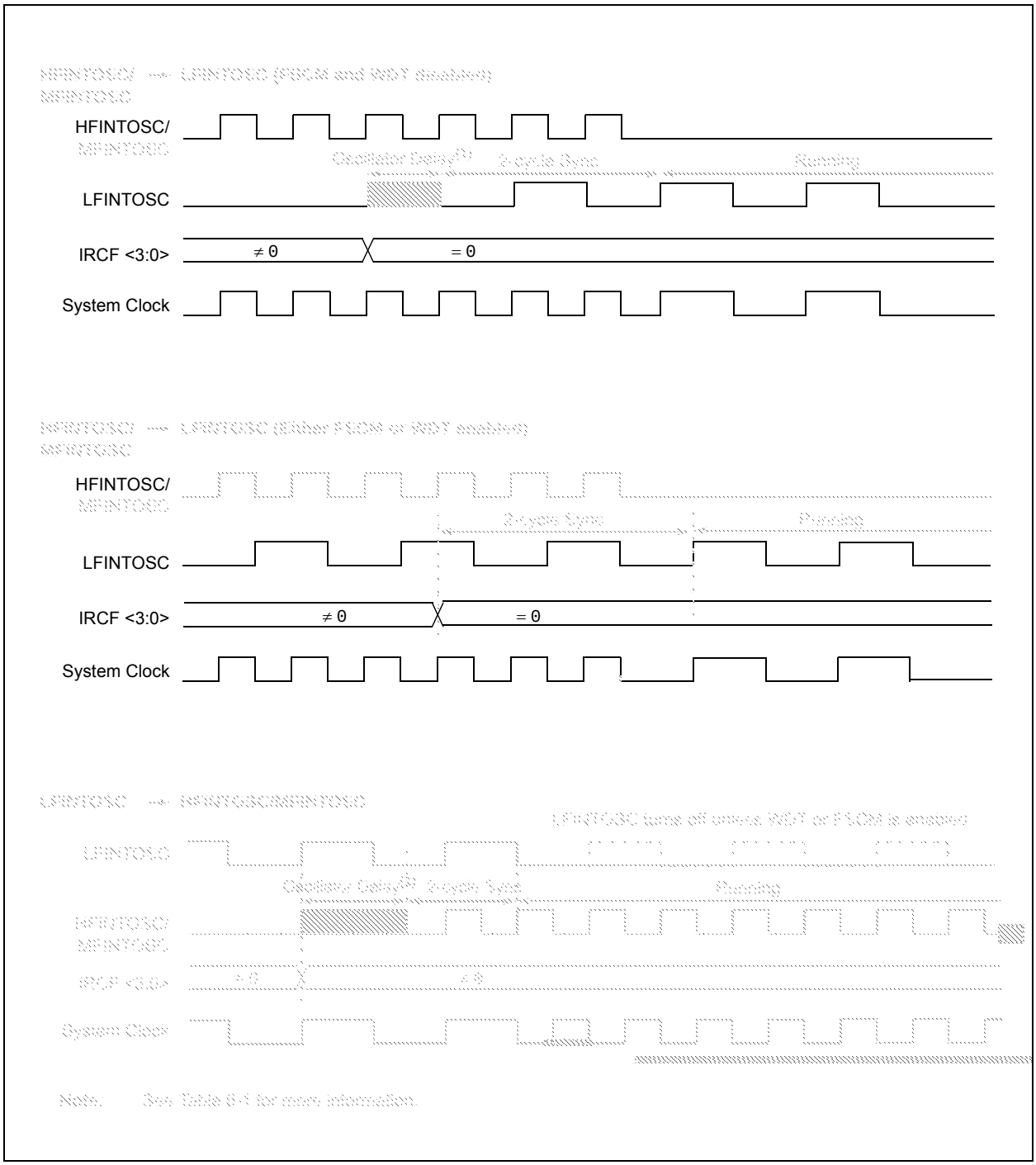
3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

6.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended, unless either FSCM or Two-Speed Start-Up are enabled. In this case, code will continue to execute at the selected INTOSC frequency while the OST is counting. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 6.4 "Two-Speed Clock Start-up Mode"**).

FIGURE 6-7: INTERNAL OSCILLATOR SWITCH TIMING



7.1 Operation

Interrupts are disabled upon any device Reset. They are enabled by setting the following bits:

- GIE bit of the INTCON register
- Interrupt Enable bit(s) for the specific interrupt event(s)
- PEIE bit of the INTCON register (if the Interrupt Enable bit of the interrupt event is contained in the PIE1 or PIE2 registers)

The INTCON, PIR1 and PIR2 registers record individual interrupts via interrupt flag bits. Interrupt flag bits will be set, regardless of the status of the GIE, PEIE and individual interrupt enable bits.

The following events happen when an interrupt event occurs while the GIE bit is set:

- Current prefetched instruction is flushed
- GIE bit is cleared
- Current Program Counter (PC) is pushed onto the stack
- Critical registers are automatically saved to the shadow registers (See **"Section 7.5 "Automatic Context Saving"**)
- PC is loaded with the interrupt vector 0004h

The firmware within the Interrupt Service Routine (ISR) should determine the source of the interrupt by polling the interrupt flag bits. The interrupt flag bits must be cleared before exiting the ISR to avoid repeated interrupts. Because the GIE bit is cleared, any interrupt that occurs while executing the ISR will be recorded through its interrupt flag, but will not cause the processor to redirect to the interrupt vector.

The `RETFIE` instruction exits the ISR by popping the previous address from the stack, restoring the saved context from the shadow registers and setting the GIE bit.

For additional information on a specific interrupt's operation, refer to its peripheral chapter.

Note 1:	Individual interrupt flag bits are set, regardless of the state of any other enable bits.
2:	All interrupts will be ignored while the GIE bit is cleared. Any interrupt occurring while the GIE bit is clear will be serviced when the GIE bit is set again.

7.2 Interrupt Latency

Interrupt latency is defined as the time from when the interrupt event occurs to the time code execution at the interrupt vector begins. The latency for synchronous interrupts is three or four instruction cycles. For asynchronous interrupts, the latency is three to five instruction cycles, depending on when the interrupt occurs. See Figure 7-2 and Figure 7-3 for more details.

TABLE 9-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Exit Sleep + System Clock = XT, HS, LP	Cleared until the end of OST
Change INTOSC divider (IRCF bits)	Unaffected

12.8 Register Definitions: PPS Input Selection

REGISTER 12-1: xxxPPS: PERIPHERAL xxx INPUT SELECTION (PIC16(L)F1704)

U-0	U-0	U-0	R/W-q/u	R/W-q/u	R/W-q/u	R/W-q/u	R/W-q/u
—	—	—	xxxPPS<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = value depends on peripheral

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **xxxPPS<4:0>:** Peripheral xxx Input Selection bits

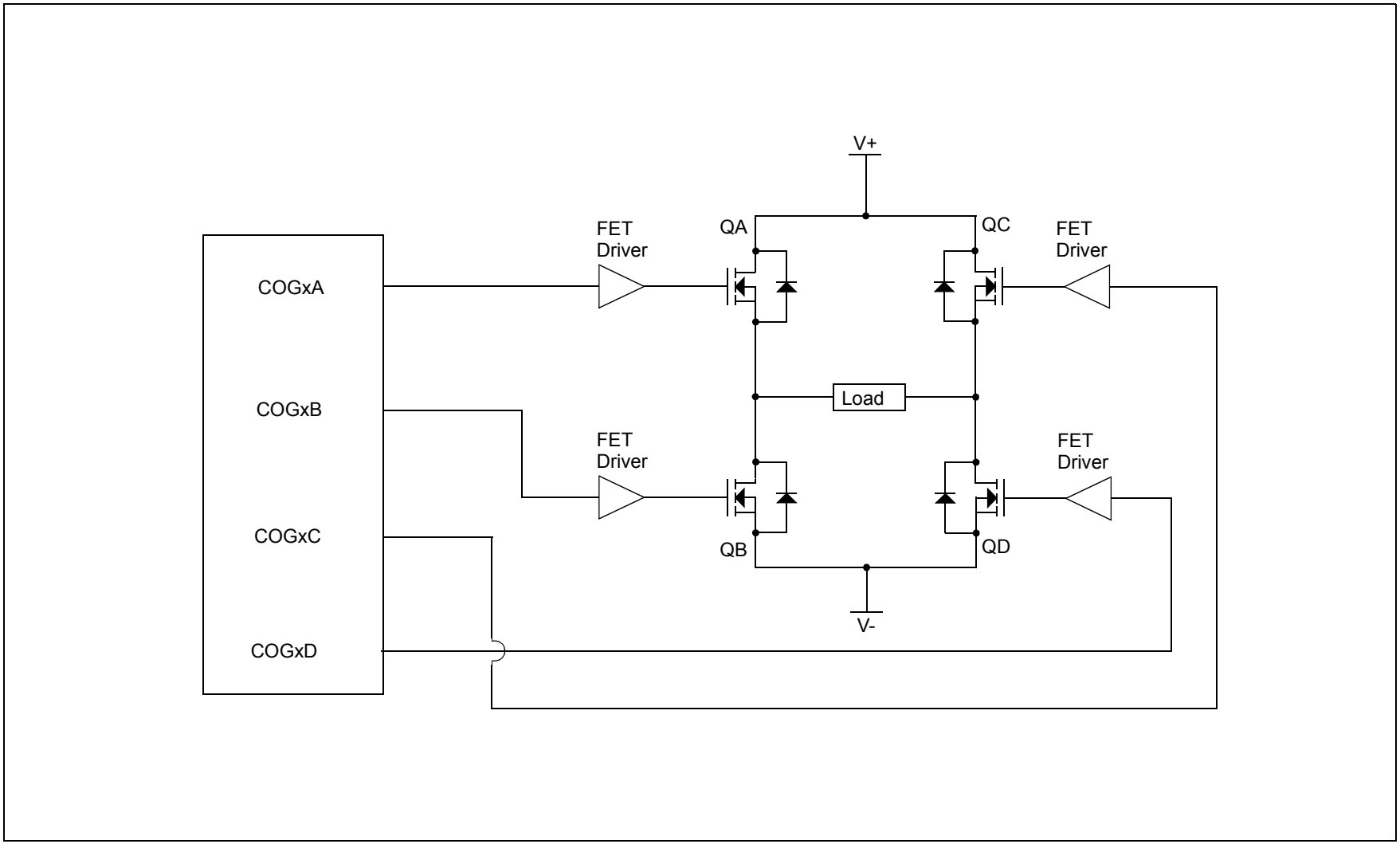
11xxx = Reserved. Do not use.

1011x = Reserved. Do not use.
10101 = Peripheral input is RC5
10100 = Peripheral input is RC4
10011 = Peripheral input is RC3
10010 = Peripheral input is RC2
10001 = Peripheral input is RC1
10000 = Peripheral input is RC0

01xxx = Reserved. Do not use.

0011X = Reserved. Do not use.
00101 = Peripheral input is RA5
00100 = Peripheral input is RA4
00011 = Peripheral input is RA3
00010 = Peripheral input is RA2
00001 = Peripheral input is RA1
00000 = Peripheral input is RA0

FIGURE 18-1: EXAMPLE OF FULL-BRIDGE APPLICATION



19.6 Register Definitions: CLC Control

REGISTER 19-1: CLCxCON: CONFIGURABLE LOGIC CELL CONTROL REGISTER

R/W-0/0	U-0	R-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
LCxEN	—	LCxOUT	LCxINTP	LCxINTN	LCxMODE<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxEN:** Configurable Logic Cell Enable bit
1 = Configurable logic cell is enabled and mixing input signals
0 = Configurable logic cell is disabled and has logic zero output

bit 6 **Unimplemented:** Read as ‘0’

bit 5 **LCxOUT:** Configurable Logic Cell Data Output bit
Read-only: logic cell output data, after LCxPOL; sampled from lcx_out wire.

bit 4 **LCxINTP:** Configurable Logic Cell Positive Edge Going Interrupt Enable bit
1 = CLCxIF will be set when a rising edge occurs on lcx_out
0 = CLCxIF will not be set

bit 3 **LCxINTN:** Configurable Logic Cell Negative Edge Going Interrupt Enable bit
1 = CLCxIF will be set when a falling edge occurs on lcx_out
0 = CLCxIF will not be set

bit 2-0 **LCxMODE<2:0>:** Configurable Logic Cell Functional Mode bits
111 = Cell is 1-input transparent latch with S and R
110 = Cell is J-K flip-flop with R
101 = Cell is 2-input D flip-flop with R
100 = Cell is 1-input D flip-flop with S and R
011 = Cell is S-R latch
010 = Cell is 4-input AND
001 = Cell is OR-XOR
000 = Cell is AND-OR

20.3 Register Definitions: ADC Control

REGISTER 20-1: ADCON0: ADC CONTROL REGISTER 0

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-2 **CHS<4:0>:** Analog Channel Select bits

11111 = FVR_Buffer1 Output(2)
11110 = DAC_output(1)
11101 = Temperature Indicator(3)
11100 = Reserved. No channel connected
11011 = Reserved. No channel connected.
•
•
•
01100 = Reserved. No channel connected.
01011 = AN11
01010 = AN10
01001 = AN9
01000 = AN8
00111 = AN7
00110 = AN6
00101 = AN5
00100 = AN4
00011 = AN3
00010 = AN2
00001 = AN1
00000 = AN0

bit 1 **GO/$\overline{\text{DONE}}$:** ADC Conversion Status bit

1 = ADC conversion cycle in progress. Setting this bit starts an ADC conversion cycle.
This bit is automatically cleared by hardware when the ADC conversion has completed.
0 = ADC conversion completed/not in progress

bit 0 **ADON:** ADC Enable bit

1 = ADC is enabled
0 = ADC is disabled and consumes no operating current

Note 1: See **Section 22.0 "8-Bit Digital-to-Analog Converter (DAC1) Module"** for more information.
2: See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.
3: See **Section 15.0 "Temperature Indicator Module"** for more information.

FIGURE 25-3: TIMER1 GATE ENABLE MODE

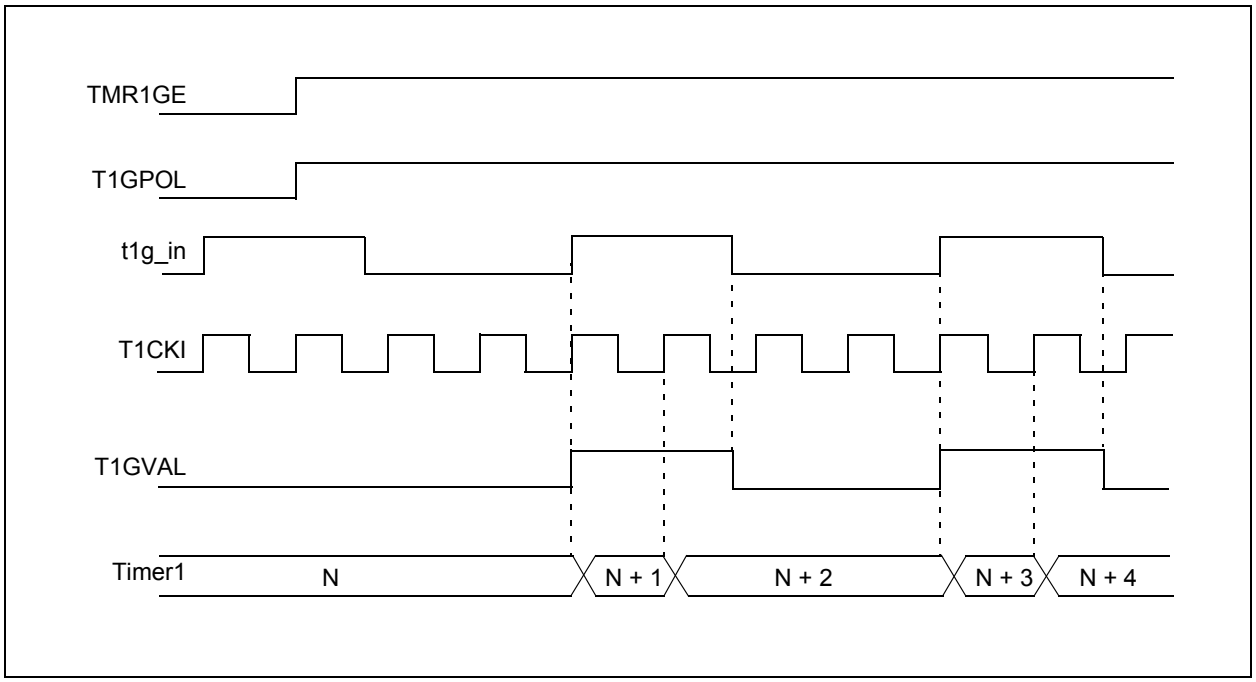
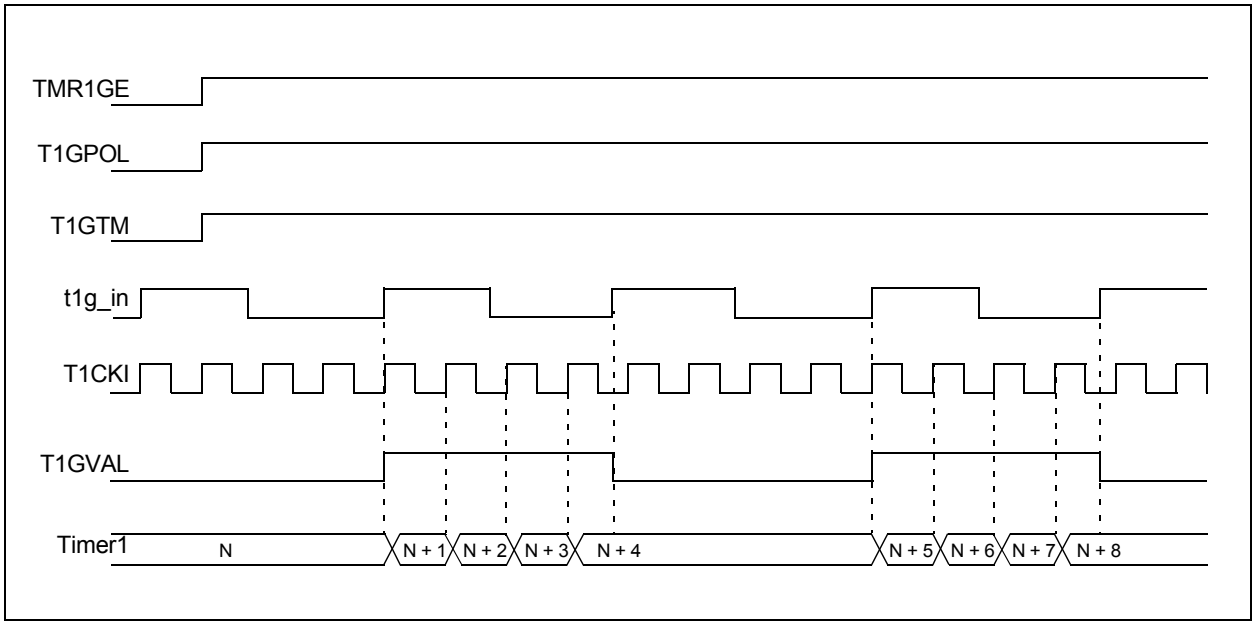


FIGURE 25-4: TIMER1 GATE TOGGLE MODE



28.2.4 SPI SLAVE MODE

In Slave mode, the data is transmitted and received as external clock pulses appear on SCK. When the last bit is latched, the SSPIF interrupt flag bit is set.

Before enabling the module in SPI Slave mode, the clock line must match the proper Idle state. The clock line can be observed by reading the SCK pin. The Idle state is determined by the CKP bit of the SSPCON1 register.

While in Slave mode, the external clock is supplied by the external clock source on the SCK pin. This external clock must meet the minimum high and low times as specified in the electrical specifications.

While in Sleep mode, the slave can transmit/receive data. The shift register is clocked from the SCK pin input and when a byte is received, the device will generate an interrupt. If enabled, the device will wake-up from Sleep.

28.2.4.1 Daisy-Chain Configuration

The SPI bus can sometimes be connected in a daisy-chain configuration. The first slave output is connected to the second slave input, the second slave output is connected to the third slave input, and so on. The final slave output is connected to the master input. Each slave sends out, during a second group of clock pulses, an exact copy of what was received during the first group of clock pulses. The whole chain acts as one large communication shift register. The daisy-chain feature only requires a single Slave Select line from the master device.

Figure 28-7 shows the block diagram of a typical daisy-chain connection when operating in SPI mode.

In a daisy-chain configuration, only the most recent byte on the bus is required by the slave. Setting the BOEN bit of the SSPCON3 register will enable writes to the SSPBUF register, even if the previous byte has not been read. This allows the software to ignore data that may not apply to it.

28.2.5 SLAVE SELECT SYNCHRONIZATION

The Slave Select can also be used to synchronize communication. The Slave Select line is held high until the master device is ready to communicate. When the Slave Select line is pulled low, the slave knows that a new transmission is starting.

If the slave fails to receive the communication properly, it will be reset at the end of the transmission, when the Slave Select line returns to a high state. The slave is then ready to receive a new transmission when the Slave Select line is pulled low again. If the Slave Select line is not used, there is a risk that the slave will eventually become out of sync with the master. If the slave misses a bit, it will always be one bit off in future transmissions. Use of the Slave Select line allows the slave and master to align themselves at the beginning of each transmission.

The $\overline{SS}$ pin allows a Synchronous Slave mode. The SPI must be in Slave mode with $\overline{SS}$ pin control enabled (SSPCON1<3:0> = 0100).

When the $\overline{SS}$ pin is low, transmission and reception are enabled and the SDO pin is driven.

When the $\overline{SS}$ pin goes high, the SDO pin is no longer driven, even if in the middle of a transmitted byte and becomes a floating output. External pull-up/pull-down resistors may be desirable depending on the application.

Note 1:	When the SPI is in Slave mode with $\overline{SS}$ pin control enabled (SSPCON1<3:0> = 0100), the SPI module will reset if the $\overline{SS}$ pin is set to VDD.
2:	When the SPI is used in Slave mode with CKE set; the user must enable $\overline{SS}$ pin control.
3:	While operated in SPI Slave mode the SMP bit of the SSPSTAT register must remain clear.

When the SPI module resets, the bit counter is forced to '0'. This can be done by either forcing the $\overline{SS}$ pin to a high level or clearing the SSPEN bit.

FIGURE 28-9: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

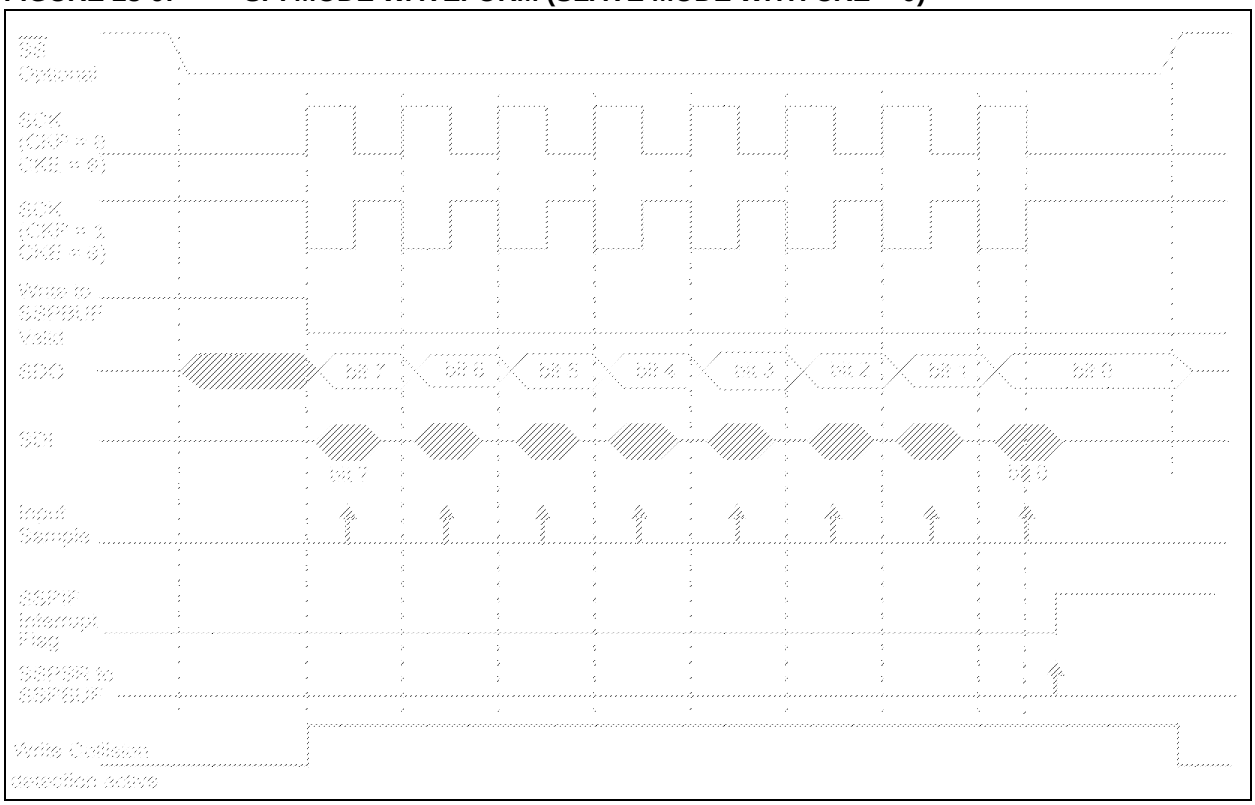


FIGURE 28-10: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)

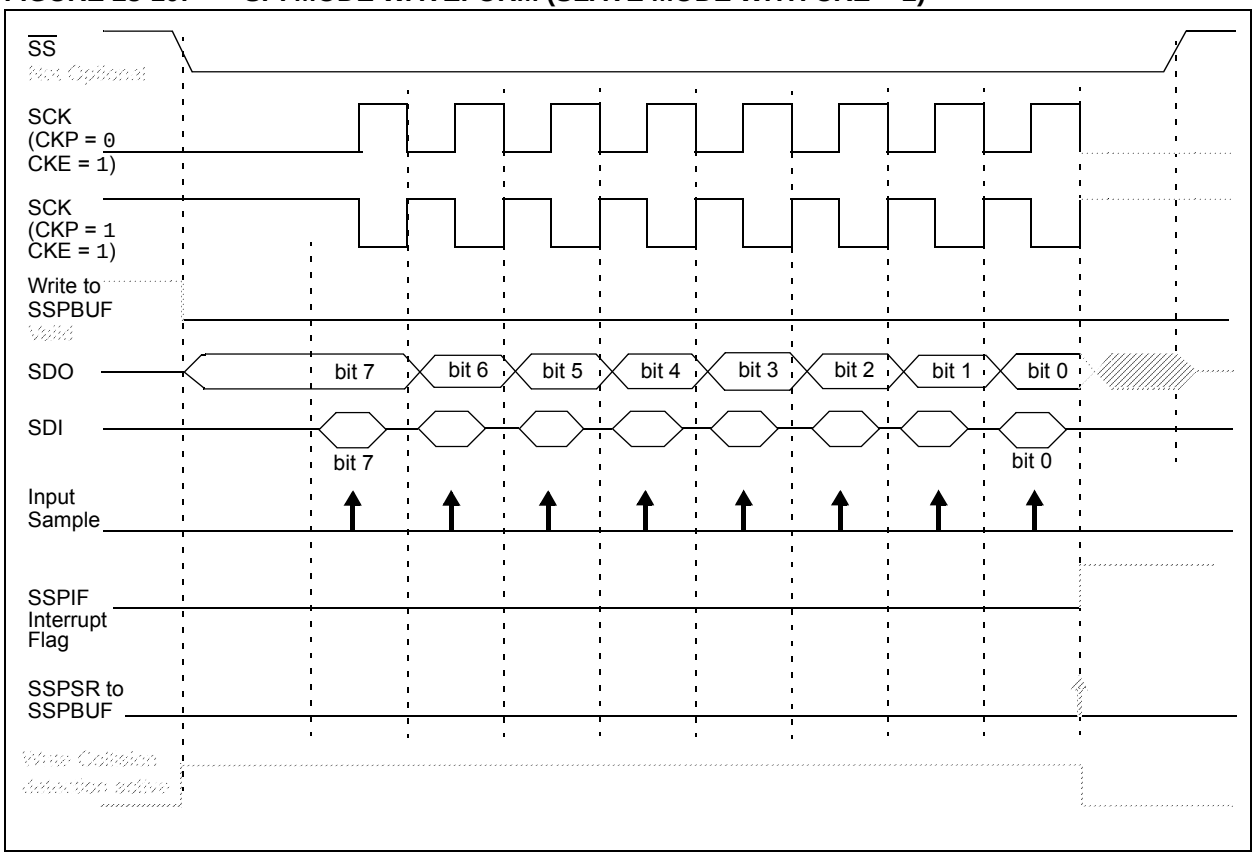
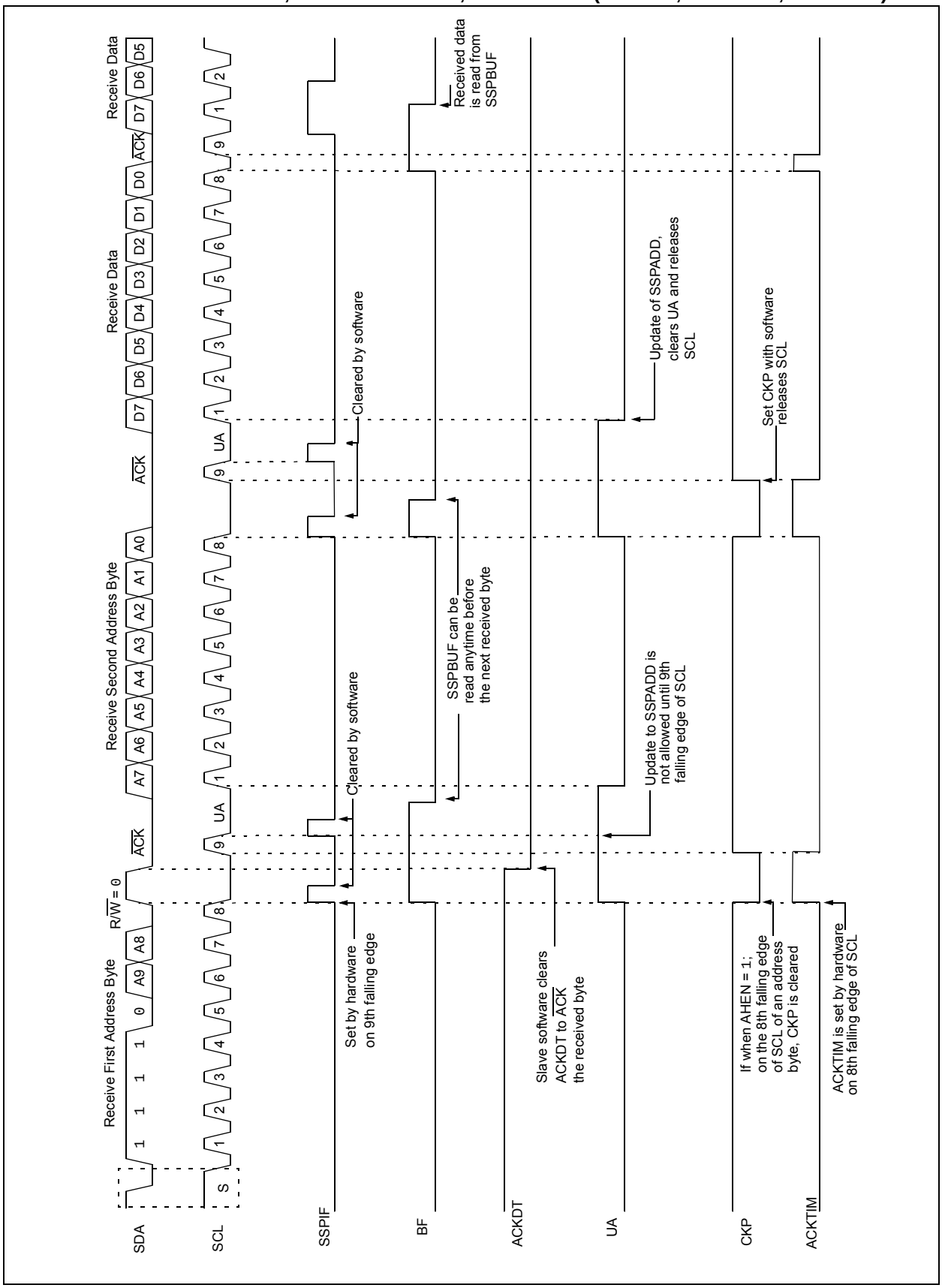


FIGURE 28-21: I²C SLAVE, 10-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 0)



28.6.13.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

a) After the SDA pin has been deasserted and allowed to float high, SDA is sampled low after the BRG has timed out (Case 1).

b) After the SCL pin is deasserted, SCL is sampled low before SDA goes high (Case 2).

The Stop condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSPADD and counts down to zero. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 28-38). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 28-39).

FIGURE 28-38: BUS COLLISION DURING A STOP CONDITION (CASE 1)

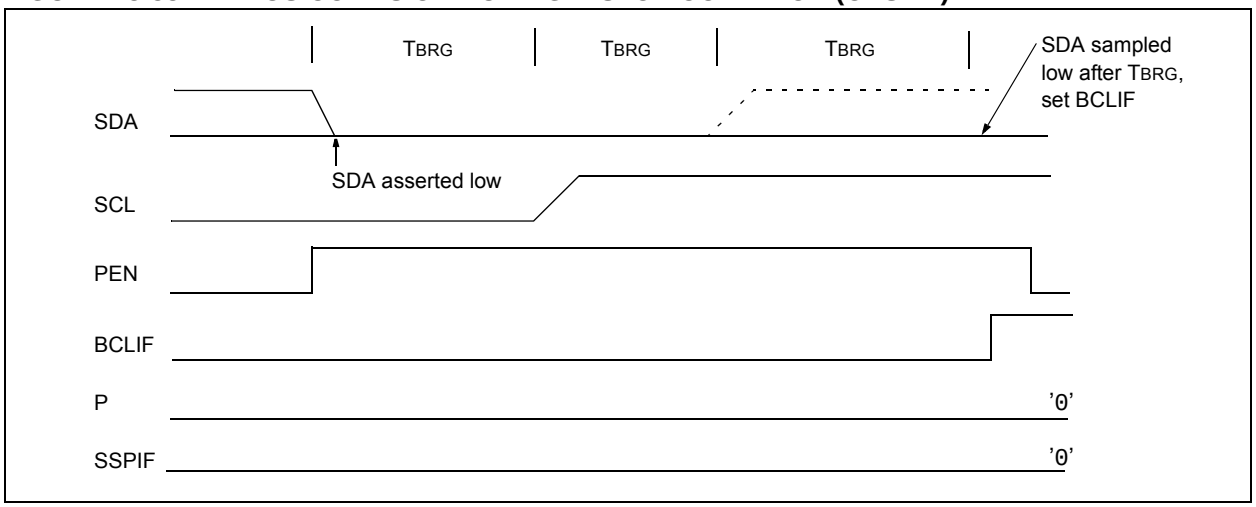
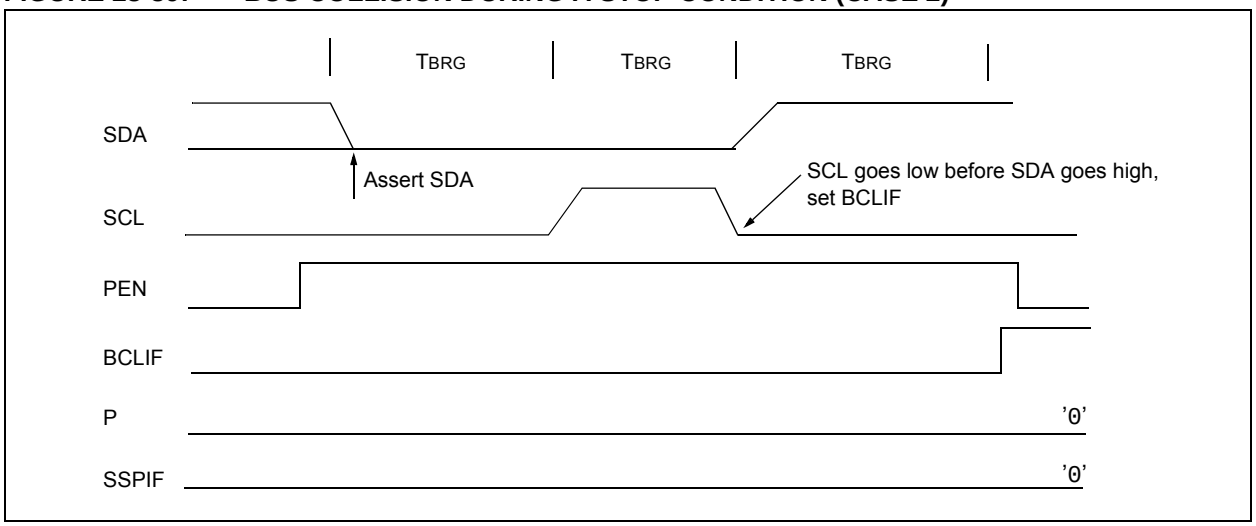


FIGURE 28-39: BUS COLLISION DURING A STOP CONDITION (CASE 2)



REGISTER 29-2: RC1STA: RECEIVE STATUS AND CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-0/0	R-0/0	R-0/0
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-Bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit
Asynchronous mode:
Don't care
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave
Don't care

bit 4 **CREN:** Continuous Receive Enable bit
Asynchronous mode:
1 = Enables receiver
0 = Disables receiver
Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enable interrupt and load the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit
Asynchronous mode 8-bit (RX9 = 0):
Don't care

bit 2 **FERR:** Framing Error bit
1 = Framing error (can be updated by reading RCREG register and receive next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit
1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** Ninth bit of Received Data
This can be address/data bit or a parity bit and must be calculated by user firmware.

RETFIE **Return from Interrupt**

Syntax: [*label*] RETFIE k

Operands: None

Operation: TOS → PC,
1 → GIE

Status Affected: None

Description: Return from Interrupt. Stack is POPed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a 2-cycle instruction.

Words: 1

Cycles: 2

Example:

```
RETFIE
```

After Interrupt
PC = TOS
GIE = 1

RETLW **Return with literal in W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W);
TOS → PC

Status Affected: None

Description: The W register is loaded with the 8-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a 2-cycle instruction.

Words: 1

Cycles: 2

Example:

```
CALL TABLE;W contains table
    ;offset value
•   ;W now has table value
•
•
ADDWF PC  ;W = offset
RETLW k1  ;Begin table
RETLW k2  ;
•
•
•
RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN

Operands: None

Operation: TOS → PC

Status Affected: None

Description: Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a 2-cycle instruction.

RLF **Rotate Left f through Carry**

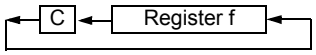
Syntax: [*label*] RLF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RLF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

Note: Unless otherwise noted, VIN = 5V, FOSC = 500 kHz, CIN = 0.1 µF, TA = 25°C.

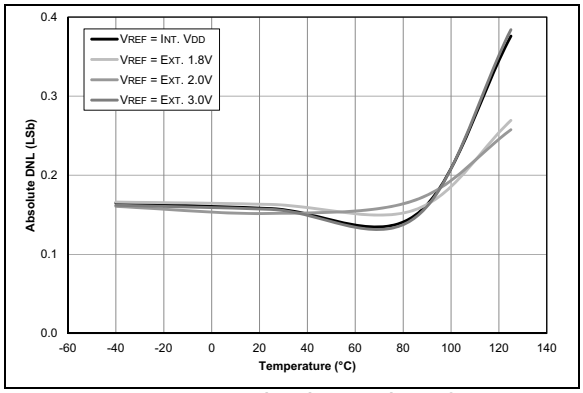


FIGURE 33-115: *Absolute Value of DAC DNL Error, VDD = 3.0V, VREF = VDD.*

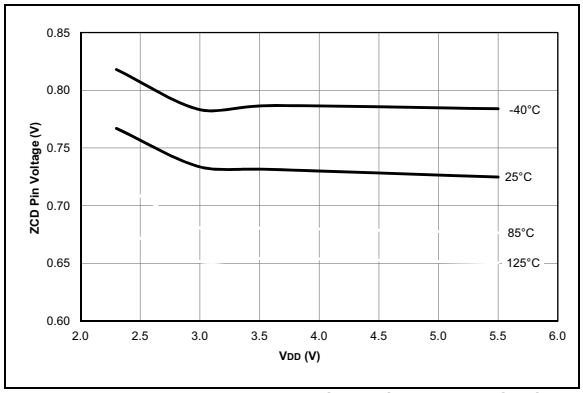


FIGURE 33-118: *ZCD Pin Voltage. Typical Measured Values.*

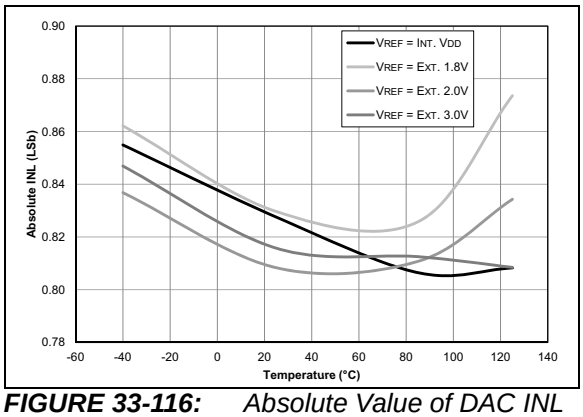


FIGURE 33-116: *Absolute Value of DAC INL Error, VDD = 3.0V, VREF = VDD.*

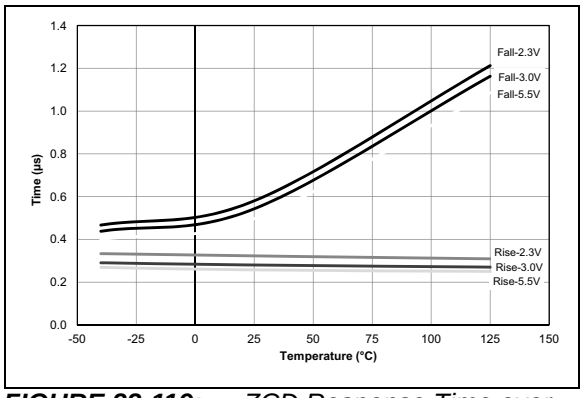


FIGURE 33-119: *ZCD Response Time over Voltage, Typical Measured Values.*

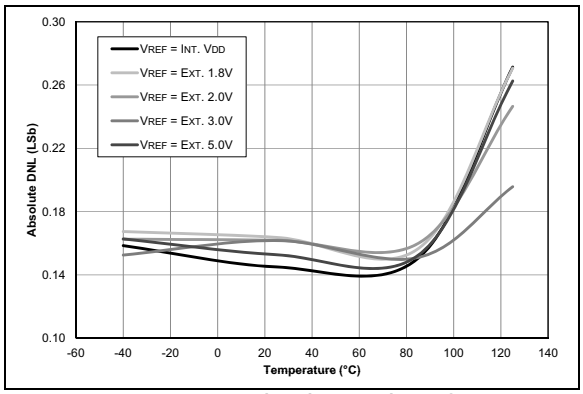


FIGURE 33-117: *Absolute Value of DAC DNL Error, VDD = 5.0V, VREF = VDD, PIC16F1704/8 Only.*

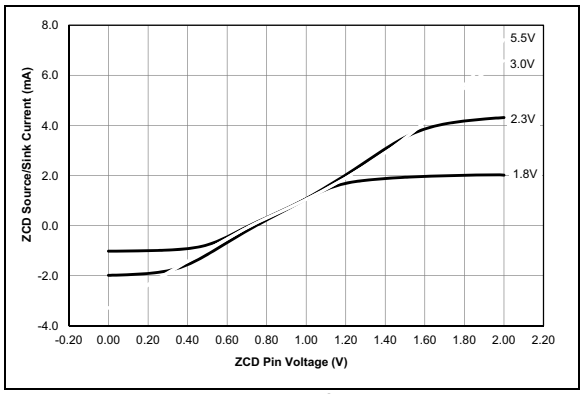
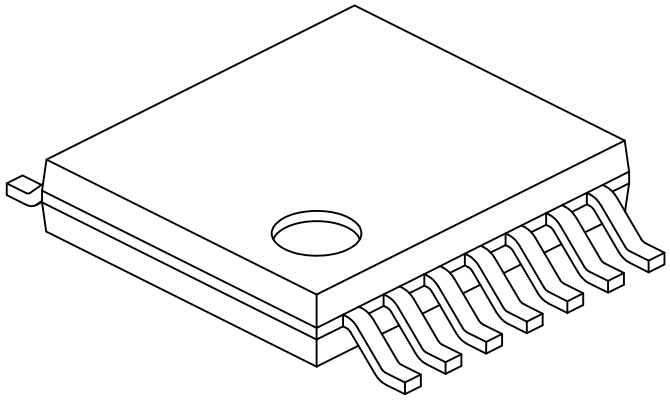


FIGURE 33-120: *ZCD Pin Current over ZCD Pin Voltage, Typical Measured Values from -40°C to 125°C.*

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		0.65 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	-	0.15
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	(L1)		1.00 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.19	-	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M

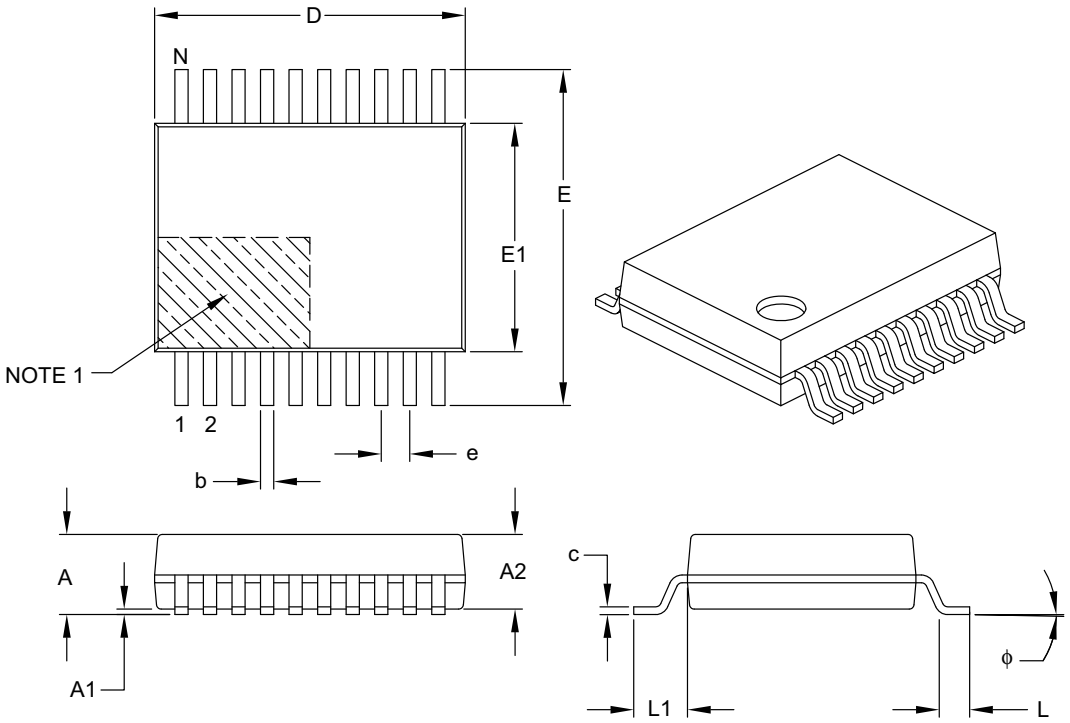
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-087C Sheet 2 of 2

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

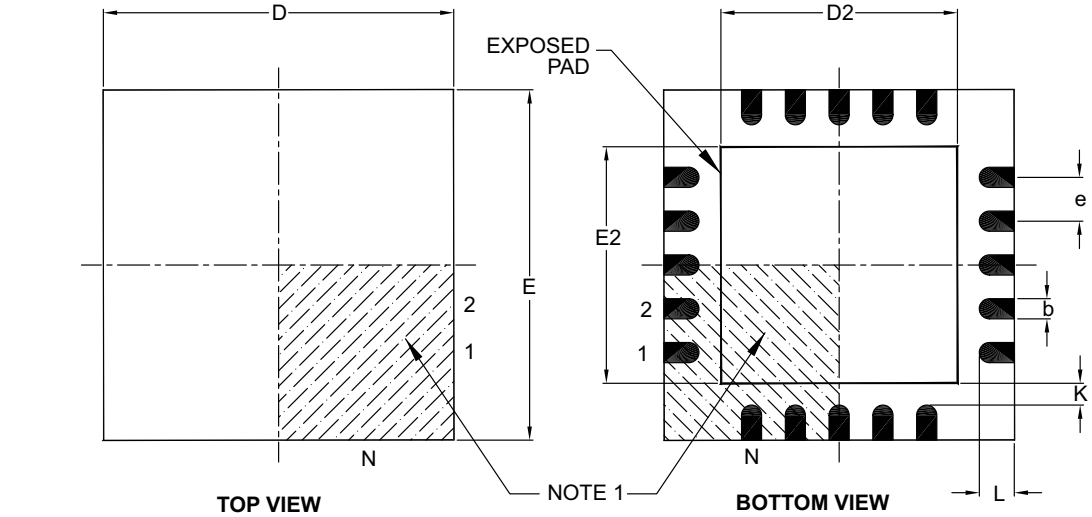
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

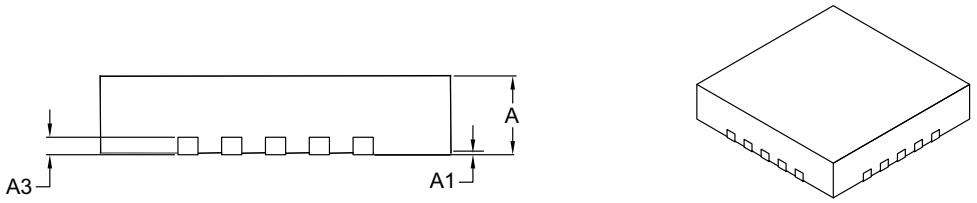
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

20-Lead Plastic Quad Flat, No Lead Package (ML) – 4x4x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.60	2.70	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.60	2.70	2.80
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-126B